October 8, 2026
Elephantech Inc.

# Elephantech to Open Toyosu Advanced Packaging Center

Accelerating Manufacturing Scale-Up and Technology Adoption for Next-Generation AI Hardware

Elephantech's New Toyosu Advanced Packaging Center

Facility Preparation Underway at Toyosu Advanced Packaging Center

Elephantech Inc. (CEO: Shinya Shimizu, Headquarters: Chuo-ku, Tokyo) announces plans to commence operations at its new Toyosu Advanced Packaging Center (Toyosu APC) in March 2027. The facility will support manufacturing scale-up and advanced packaging R&D to meet surging demand for AI servers. In line with this expansion, the company will strengthen recruitment across a wide range of areas, including materials, equipment and process development.

Leveraging its proprietary nanomaterials expertise and precision inkjet technologies, Elephantech has developed innovative manufacturing processes for PCBs and package substrates, enabling higher-density interconnects while reducing environmental impact. These technologies address critical challenges in cutting-edge AI server boards, where high-speed signal transmission, greater structural density, and efficient power delivery are

increasingly essential.

One of Elephantech's key solutions, DeepVia™ HDI, has attracted market interest since its introduction. By enabling reliable metallization of higher-aspect-ratio microvias, it expands PCB design flexibility and supports improvement in system performance. Its component equipment, DK100, has already been shipped overseas for production of AI server PCBs for a leading North American chipmaker.
https://elephantech.com/en/news/press_release_20260918/

Another solution, DS-SAP™, which enables fine-line patterning and continuous via seed coverage in package substrates, is also being explored with leading North American semiconductor manufacturers through collaborations aimed at developing new substrate designs toward mass adoption.
https://elephantech.com/en/news/press_release_20260618/

Building on the momentum, Toyosu APC will provide a comprehensive environment for advanced packaging and cutting-edge PCB solution scale-up. Located in Koto-ku, Tokyo, the new center will offer approximately 6,700 $m^2$ of floor area, bringing together cleanrooms, prototyping equipment capable of processing panels up to 550 × 622 mm, covering from printing through copper electroplating, and a range of analytical instruments including AFM-IR, SEM, XRD, and XRF. As a single site integrating these capabilities, Toyosu APC aims to enhance mass production readiness, and accelerate broader adoption of Elephantech's technologies for next-generation AI servers.

Shinya Shimizu, CEO and founder of Elephantech, stated: "We are delighted to announce the establishment of Toyosu APC. Our nanomaterials technologies are emerging as key enablers for advancing AI computing performance, and we are currently working with the majority of leading AI semiconductor manufacturers on new designs. In response to strong market demand, a comprehensive facility that seamlessly combines development, prototyping, and evaluation will be necessary for our future growth. At the same time, we will bring in more talents to this sizable facility located in central Tokyo with an attractive environment. The opening of Toyosu APC will mark a new chapter for Elephantech as we strengthen our capabilities as a nanomaterials and manufacturing equipment provider and accelerate our global expansion."

**Facility Overview**

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| Name | Toyosu Advanced Packaging Center (Toyosu APC) |
| Address | 2-24-12 Edagawa, Koto-ku, Tokyo 135-0051, Japan |
| Scheduled Opening | March 2027 |
| Total Floor Are | Approximately 6,700 $m^2$ |
| Main Functions | Nanomaterials and process development, prototyping, evaluation and analysis for advanced packaging in AI server applications |

## Company Overview

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| Name | Elephantech Inc. |
| Establishment | January 2014 |
| Headquarters | 4-3-8 Hatchobori, Chuo-ku, Tokyo 104-0032, Japan |
| Representative | Shinya Shimizu, Representative Director & CEO |
| Business Description | Development, manufacturing, and sales of equipment and nanomaterials for advanced packaging |
| URL | https://elephantech.com/en/ |

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